2A SCHOTTKY BARRIER RECTIFIER CHIP SCALE PACKAGE

Product Summary

V_{RRM} (V)	I_O (A)	V_F Max (V)	I_R Max (µA)
40	2.0	0.53	150

Features and Benefits

- Low forward voltage (V_F) minimizes conduction losses and improves efficiency.
- Reduced high temperature reverse leakage; Increased reliability against thermal runaway failure in high temperature operation.
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

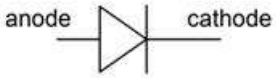
Description and Applications

The SDM2U40CSP is a 40-volt 2A Schottky Barrier Rectifier that is optimized for low forward voltage drop and low leakage current, housed in a compact chip scale package (CSP) that occupies only 1.28mm^2 board space with low profile. The low thermal resistance enables designers to meet design challenges of increasing efficiency whilst at the same time reducing board space. It is ideally suited for use in portable applications as a:

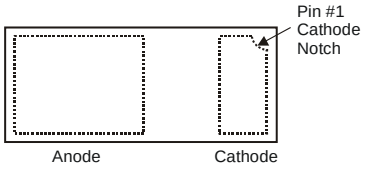
- Blocking Diode
- Boost Diode
- Switching Diode
- Reverse Protection Diode

Mechanical Data

- Case: X3-WLB1608-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 (e4)
- Polarity: Cathode Dot
- Weight: 0.001 grams (Approximate)



Device Schematic

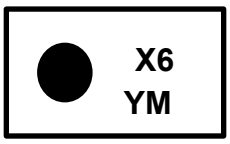


Ordering Information (Note 4)

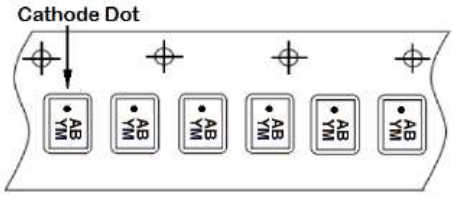
Part Number	Case	Packaging
SDM2U40CSP-7B	X3-WLB1608-2	10,000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



X6= Product Type Marking Code
YM=Date Code Marking
Y or $\overline{Y}$= Year (ex: F = 2018)
M=Month (ex: 9= September)
Dot Denotes Cathode Pin



Date Code Key

Year	2014	2015	2016	2017	2018	2019	2020
Code	B	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
Average Rectified Output Current	I_O	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	28	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	135	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	$R_{\theta JA}$	65	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	—	0.39	0.44	V	I_F = 1.0A, T_J = +25°C
		—	0.48	0.53		I_F = 2.0A, T_J = +25°C
Reverse Current (Note 7)	I_R	—	—	150	μA	V_R = 40V, T_J = +25°C
Junction Capacitance	C_T	—	85	—	pF	V_R = 5V, f = 1.0MHz

Notes: 5. Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
6. Device mounted on 1inch sq. copper pad, 2oz.
7. Short duration pulse test used to minimize self-heating effect.

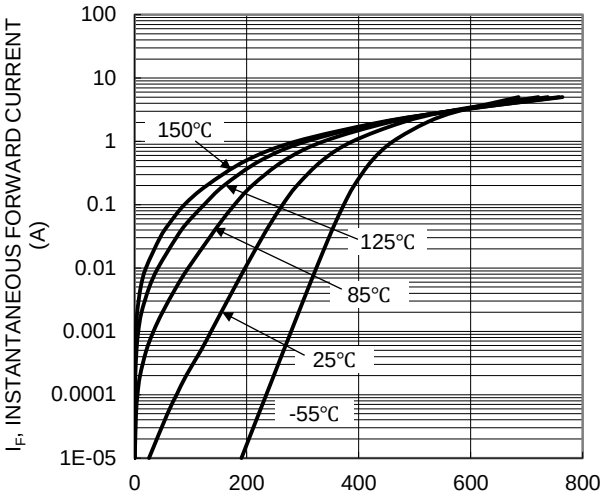


Figure 1. Typical Forward Characteristics

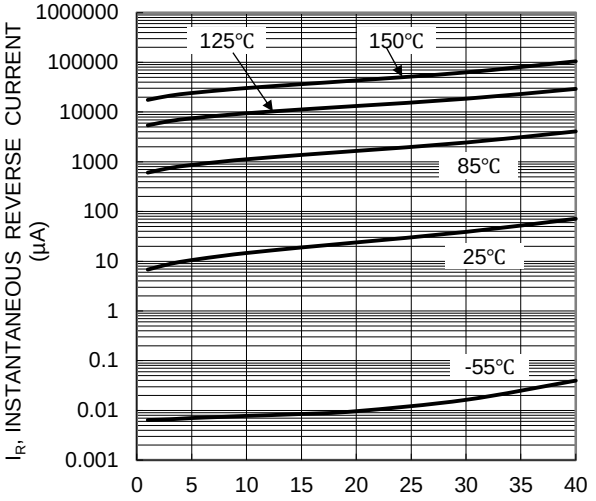


Figure 2. Typical Reverse Characteristics

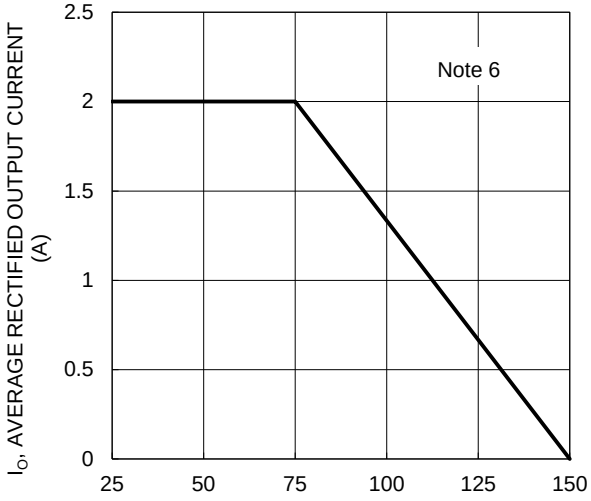


Figure 3. DC Forward Current Derating Curve

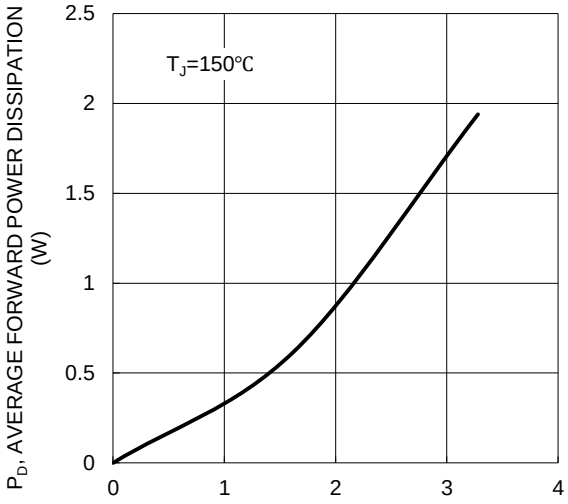


Figure 4. Forward Power Dissipation

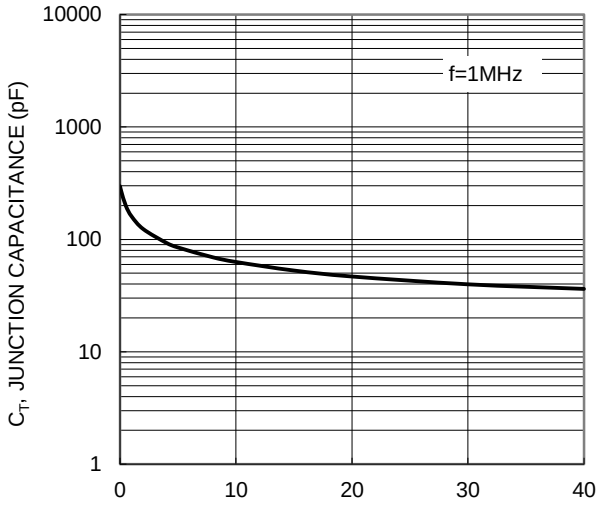
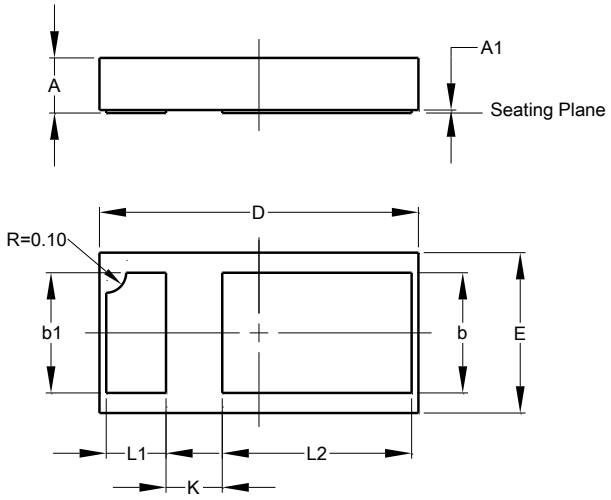


Figure 5. Typical Junction Capacitance

Package Outline Dimensions (Note 8)

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB1608-2



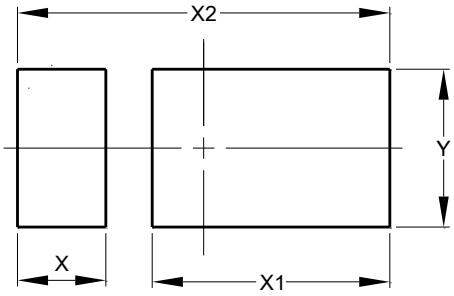
X3-WLB1608-2			
Dim	**Min**	**Max**	**Typ**
A	0.250	0.300	0.275
A1	-	0.015	-
b	-	-	0.600
b1	-	-	0.600
D	1.57	1.63	1.60
E	0.77	0.83	0.80
K	-	-	0.282
L1	0.25	0.35	0.30
L2	0.90	1.00	0.95
All Dimensions in mm			

Note 8: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB1608-2



Dimensions	Value (in mm)
X	0.385
X1	1.035
X2	1.622
Y	0.690

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